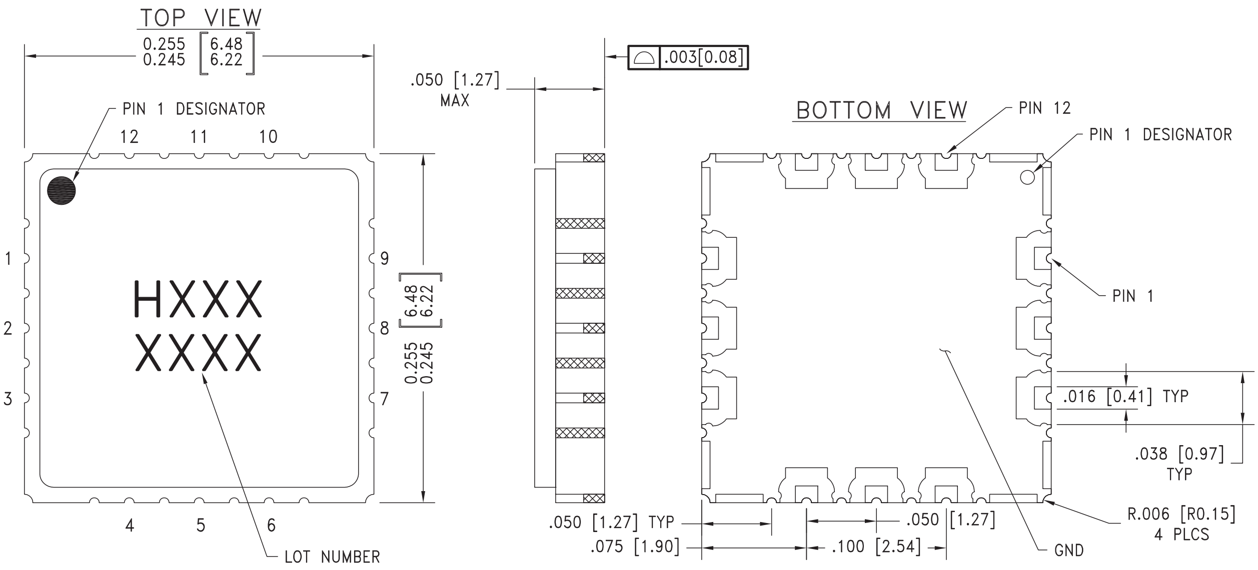
LH250 – CERAMIC HERMETIC SMT PACKAGE

LH250 Package Outline Drawing



NOTES:

1. PACKAGE MATERIAL: CERAMIC & KOVAR.
2. LEAD AND GROUND PADDLE PLATE: GOLD 40 - 80 MICROINCHES.
3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
4. LEAD SPACING TOLERANCE IN NON-CUMULATIVE.
5. PAD BUR LENGTH 0.15mm MAX. PAD BUR HEIGHT 0.25mm MAX.
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

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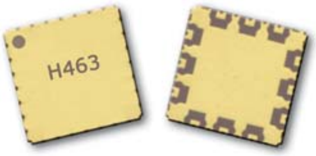
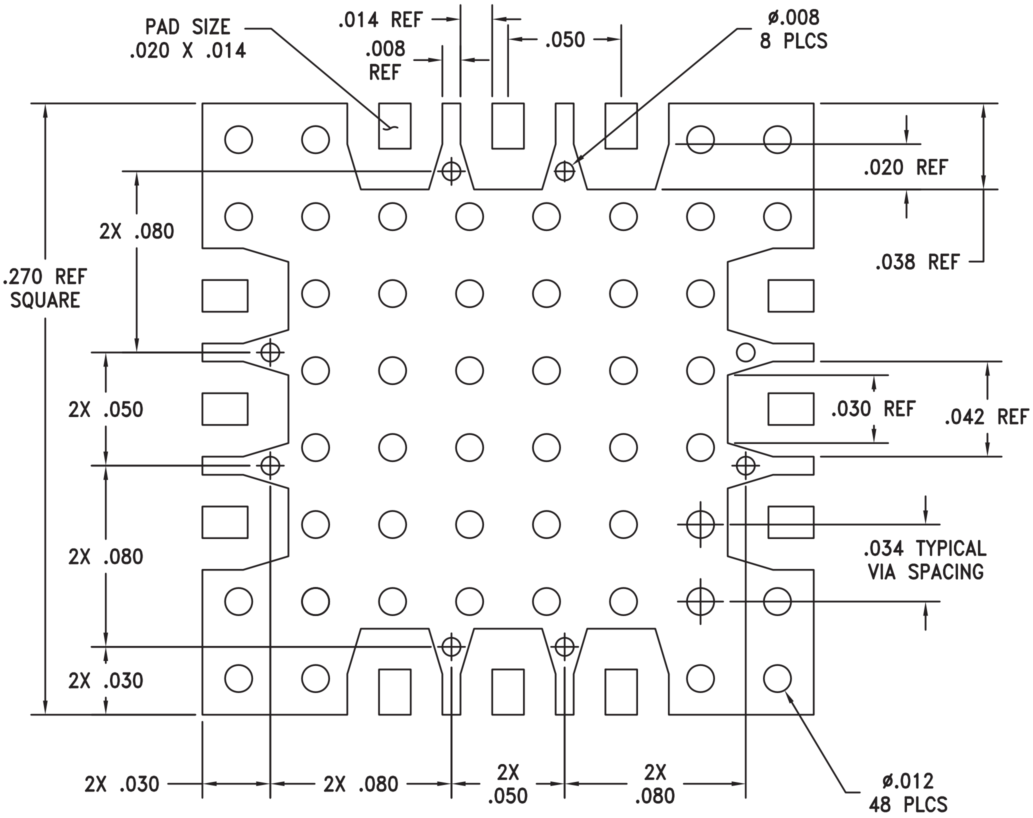
Suggested LH250 PCB Land Pattern





NOTES:

1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.